

OPTOELECTRONIC PACKAGE AND FABRICATION METHOD

Abstract of Disclosure

An optoelectronic package is fabricated by a method which includes: positioning an optical device within a window of a substrate active-side up and below a top substrate surface; filling the window with an optical polymer material; planarizing surfaces of the optical polymer material and the substrate; patterning waveguide material over the optical polymer material and the substrate to form an optical interconnection path and to form a mirror to reflect light from the optical device to the interconnection path; and forming a via to expose a bond pad of the optical device.

Figures